External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Paste	Lead alloy	Tin (Sn)	7440-31-5	0.00103	5.0	0.05
	Lead alloy	Lead (Pb)	7439-92-1	0.01743	85.0	0.85
	Lead alloy	Antimony (Sb)	7440-36-0	0.00205	10.0	0.1
			Subtotal	0.02051	100	1
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01087	100.0	0.53014
	Pure metal	Aluminium (Al)	7429-90-5	0.00098	100.0	0.04771
			Subtotal	0.01185	200	0.57785
Die	Doped silicon	Silicon (Si)	7440-21-3	0.48389	100.0	23.6
			Subtotal	0.48389	100	23.6
Solder Paste	Pure metal	Tin (Sn)	7440-31-5	0.06049	5.0	2.95
	Pure metal	Silver (Ag)	7440-22-4	0.03024	2.5	1.475
	Pure metal	Lead (Pb)	7439-92-1	1.11899	92.5	54.575
			Subtotal	1.20972	100	59
Isolator	Aluminium alloy	Aluminium Trioxide (Al2O3)	1344-28-1	3.85469	100.0	188
			Subtotal	3.85469	100	188
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00517	0.03	0.252
	Copper alloy	Iron (Fe)	7439-89-6	0.01895	0.11	0.924
	Copper alloy	Copper (Cu)	7440-50-8	17.19552	99.84	838.656
	Copper alloy	Silver (Ag)	7440-22-4	0.00344	0.02	0.168
	Copper alloy	Phosphorous (P)	7723-14-0	0.01647	0.03	0.8034
	Copper alloy	Iron (Fe)	7439-89-6	0.0604	0.11	2.9458
	Copper alloy	Copper (Cu)	7440-50-8	54.83193	99.86	2674.2508
			Subtotal	72.13188	200	3518
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.06151	100.0	3
			Subtotal	0.06151	100	3
Mould Compound	polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	0.35562	1.6	17.344
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.44469	6.5	70.46
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	2.88938	13.0	140.92
	Filler	Silica fused	60676-86-0	17.33626	78.0	845.52
	Carbon Black	Carbon black	1333-86-4	0.15558	0.7	7.588
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.04445	0.2	2.168
			Subtotal	22.22598	100	1084
			Total	100.00003	100	4877.17785

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